

12/18/00



JC970 U.S. PTO

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Atty. Docket No. AMAT/5614/CMP/CMP/RKK

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application
Assistant Commissioner of Patents and Trademarks
Washington, D.C. 20231

Re: Inventor(s): WEI-YUNG HSU, LIANG-YUH CHEN, RATSON MORAD, DANIEL A. CARL
and SASSON SOMEKH
Title: INTEGRATED MULTI-STEP GAP FILL AND ALL FEATURE PLANARIZATION FOR
CONDUCTIVE MATERIALS

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09/739139



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Transmitted herewith is the patent application identified above, including:

- ☒ Specification, claims and abstract, totaling 36 pages.
☒ Drawings totaling 15 pages, ☒ Formal ☐ Informal.
☒ Executed Declaration and Power of Attorney.

Information Disclosure Statement w/ Form 1449 and References.

☒ Assignment of the invention to **Applied Materials, Inc.**

☒ Assignment Recordation Cover Sheet

FEE CALCULATION

Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	88	-20=	68	x \$18.00	\$1224.00
Independent Claims	6	-3=	3	x \$80.00	\$ 240.00
Basic Filing Fee				\$710.00	\$ 710.00
TOTAL FEES					\$2174.00

- ☒ The Commissioner is hereby authorized to charge \$2174.00 to Deposit Account No. 50-1074/5614/CMP/CMP/RKK.
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 50-1074/5614/CMP/CMP/RKK. A duplicate copy of this transmittal is enclosed.

- ☒ Please address all future correspondence to:

PATENT COUNSEL
APPLIED MATERIALS, INC.
Legal Affairs Department
P.O.BOX 450A
Santa Clara, CA. 95052

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231.

Express Mail Receipt No. EL684621317US

Date of Deposit 12-18-2000

Signature Robert W. Mulcahy

Respectfully submitted,

Robert W. Mulcahy
Registration No. 25,436